

DATA SHEET

74LV04 Hex inverter

Product specification
Supersedes data of 1997 Feb 03
IC24 Data Handbook

1998 Apr 20

Hex inverter

74LV04

FEATURES

- Wide operating voltage: 1.0 to 5.5 V
- Optimized for low voltage applications: 1.0 to 3.6 V
- Accepts TTL input levels between $V_{CC} = 2.7$ V and $V_{CC} = 3.6$ V
- Typical V_{OLP} (output ground bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_{amb} = 25^{\circ}\text{C}$
- Typical V_{OHV} (output V_{OH} undershoot) > 2 V at $V_{CC} = 3.3$ V, $T_{amb} = 25^{\circ}\text{C}$
- Output capability: standard
- I_{CC} category: SSI

DESCRIPTION

The 74LV04 is a low-voltage Si-gate CMOS device that is pin and function compatible with 74HC/HCT04.

The 74LV04 provides six inverting buffers.

QUICK REFERENCE DATA

$GND = 0$ V; $T_{amb} = 25^{\circ}\text{C}$; $t_r = t_f \leq 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay nA to nY	$C_L = 15$ pF; $V_{CC} = 3.3$ V	6	ns
C_I	Input capacitance		3.5	pF
C_{PD}	Power dissipation capacitance per gate	See Notes NO TAG and 2	21	pF

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz; C_L = output load capacitance in pF;
 f_o = output frequency in MHz; V_{CC} = supply voltage in V;
 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
2. The condition is V_1 is $V_1 = GND$ to V_{CC} .

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	-40°C to $+125^{\circ}\text{C}$	74LV04 N	74LV04 N	SOT27-1
14-Pin Plastic SO	-40°C to $+125^{\circ}\text{C}$	74LV04 D	74LV04 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to $+125^{\circ}\text{C}$	74LV04 DB	74LV04 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to $+125^{\circ}\text{C}$	74LV04 PW	74LV04PW DH	SOT402-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 3, 5, 9, 11, 13	1A – 6A	Data inputs
2, 4, 6, 8, 10, 12	1Y – 6Y	Data outputs
7	GND	Ground (0 V)
14	V_{CC}	Positive supply voltage

FUNCTION TABLE

INPUTS	OUTPUTS
nA	nY
L	H
H	L

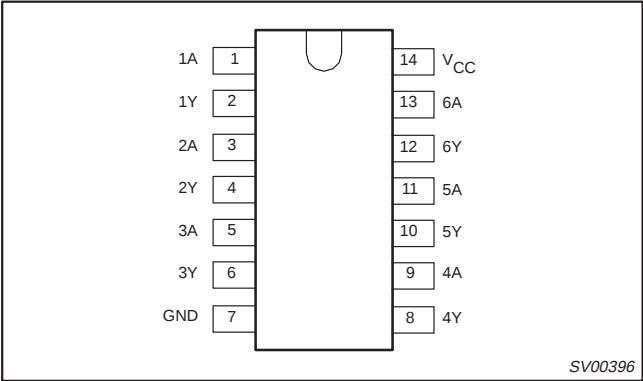
NOTES:

H = HIGH voltage level
L = LOW voltage level

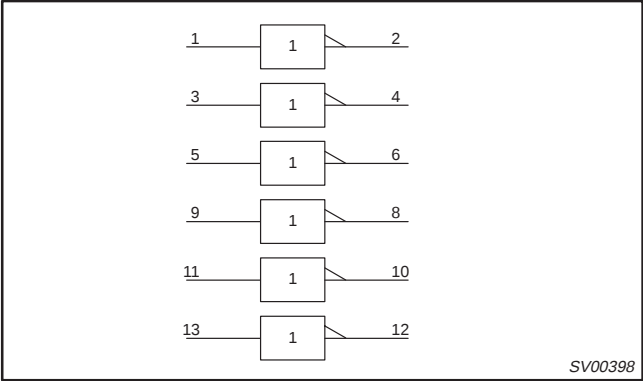
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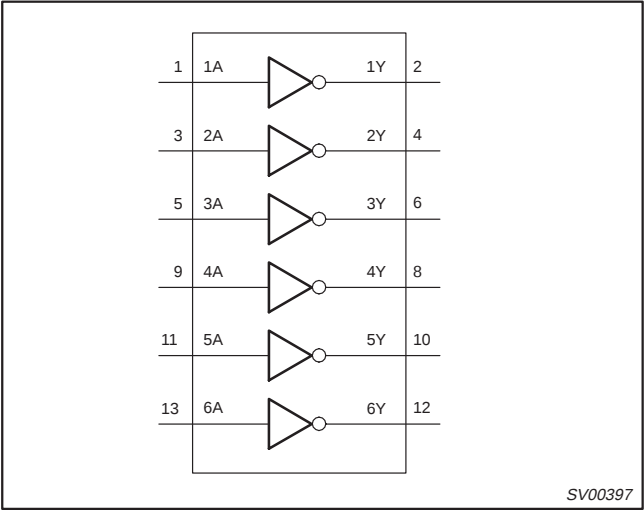
PIN CONFIGURATION



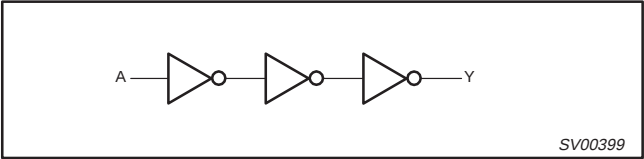
LOGIC SYMBOL (IEEE/IEC)



LOGIC SYMBOL



LOGIC DIAGRAM (ONE INVERTER)



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V _{CC}	DC supply voltage	See Note ^{NO TAG}	1.0	3.3	5.5	V
V _I	Input voltage		0	–	V _{CC}	V
V _O	Output voltage		0	–	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	–40 –40		+85 +125	°C
t _r , t _f	Input rise and fall times	V _{CC} = 1.0V to 2.0V V _{CC} = 2.0V to 2.7V V _{CC} = 2.7V to 3.6V V _{CC} = 3.6V to 5.5V	– – – –	– – – –	500 200 100 50	ns/V

NOTE:
1. The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

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ABSOLUTE MAXIMUM RATINGS NO TAG, NO TAG

In accordance with the Absolute Maximum Rating System (IEC 134).

Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		-0.5 to +7.0	V
$\pm I_{IK}$	DC input diode current	$V_I < -0.5$ or $V_I > V_{CC} + 0.5V$	20	mA
$\pm I_{OK}$	DC output diode current	$V_O < -0.5$ or $V_O > V_{CC} + 0.5V$	50	mA
$\pm I_O$	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5V$	25	mA
$\pm I_{GND}$, $\pm I_{CC}$	DC V_{CC} or GND current for types with – standard outputs		50	mA
T_{stg}	Storage temperature range		-65 to +150	°C
P_{TOT}	Power dissipation per package – plastic DIL – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			-40°C to +85°C			-40°C to +125°C		
			MIN	TYP. NO TAG	MAX	MIN	MAX	
V _{IH}	HIGH level Input voltage	V _{CC} = 1.2V	0.9			0.9		V
		V _{CC} = 2.0V	1.4			1.4		
		V _{CC} = 2.7 to 3.6V	2.0			2.0		
		V _{CC} = 4.5 to 5.5V	0.7 * V _{CC}			0.7 * V _{CC}		
V _{IL}	LOW level Input voltage	V _{CC} = 1.2V			0.3		0.3	V
		V _{CC} = 2.0V			0.6		0.6	
		V _{CC} = 2.7 to 3.6V			0.8		0.8	
		V _{CC} = 4.5 to 5.5			0.3 * V _{CC}		0.3 * V _{CC}	
V _{OH}	HIGH level output voltage; all outputs	V _{CC} = 1.2V; V _I = V _{IH} or V _{IL} ; -I _O = 100μA		1.2				V
		V _{CC} = 2.0V; V _I = V _{IH} or V _{IL} ; -I _O = 100μA	1.8	2.0		1.8		
		V _{CC} = 2.7V; V _I = V _{IH} or V _{IL} ; -I _O = 100μA	2.5	2.7		2.5		
		V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; -I _O = 100μA	2.8	3.0		2.8		
		V _{CC} = 4.5V; V _I = V _{IH} or V _{IL} ; -I _O = 100μA	4.3	4.5		4.3		
V _{OH}	HIGH level output voltage; STANDARD outputs	V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; -I _O = 6mA	2.40	2.82		2.20		V
		V _{CC} = 4.5V; V _I = V _{IH} or V _{IL} ; -I _O = 12mA	3.60	4.20		3.50		
V _{OL}	LOW level output voltage; all outputs	V _{CC} = 1.2V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		0				V
		V _{CC} = 2.0V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		0	0.2		0.2	
		V _{CC} = 2.7V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		0	0.2		0.2	
		V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		0	0.2		0.2	
		V _{CC} = 4.5V; V _I = V _{IH} or V _{IL} ; I _O = 100μA		0	0.2		0.2	
V _{OL}	LOW level output voltage; STANDARD outputs	V _{CC} = 3.0V; V _I = V _{IH} or V _{IL} ; I _O = 6mA		0.25	0.40		0.50	V
		V _{CC} = 4.5V; V _I = V _{IH} or V _{IL} ; I _O = 12mA		0.35	0.55		0.65	

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DC ELECTRICAL CHARACTERISTICS (Continued)

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			-40°C to +85°C			-40°C to +125°C		
			MIN	TYP. NO TAG	MAX	MIN	MAX	
I _I	Input leakage current	V _{CC} = 5.5V; V _I = V _{CC} or GND			1.0		1.0	μA
I _{CC}	Quiescent supply current; SSI	V _{CC} = 5.5V; V _I = V _{CC} or GND; I _O = 0			20.0		40	μA
ΔI _{CC}	Additional quiescent supply current	V _{CC} = 2.7V to 3.6V; V _I = V _{CC} – 0.6V			500		850	μA

NOTE:

1. All typical values are measured at $T_{amb} = 25^{\circ}C$.

AC CHARACTERISTICS

GND = 0V; $t_r = t_f \leq 2.5ns$; $C_L = 50pF$; $R_L = 1K\Omega$

SYMBOL	PARAMETER	WAVEFORM	CONDITION	LIMITS					UNIT
				−40 to +85°C			−40 to +125°C		
			V _{CC} (V)	MIN	TYP NO TAG	MAX	MIN	MAX	
t _{PHL} /t _{PLH}	Propagation delay nA to nY	Figure 1	1.2		40				ns
			2.0		14	20		25	
			2.7		10	15		19	
			3.0 to 3.6		8NO TAG	12		15	
			4.5 to 5.5			9		11	

NOTES:

1. Unless otherwise stated, all typical values are measured at $T_{amb} = 25^{\circ}C$
2. Typical values are measured at $V_{CC} = 3.3 V$.

AC WAVEFORMS

$V_M = 1.5 V$ at $V_{CC} \geq 2.7 V$ and $\leq 3.6 V$;
 $V_M = 0.5 \times V_{CC}$ at $V_{CC} < 2.7 V$ and $\geq 4.5 V$;
 V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

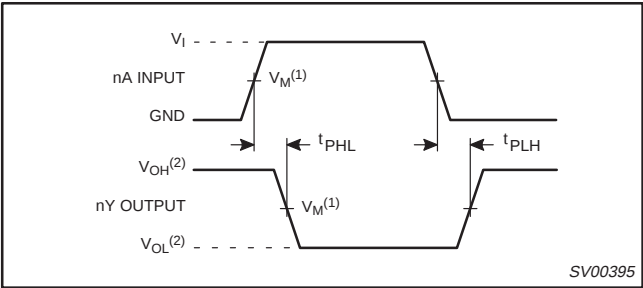


Figure 1. Input (nA) to output (nY) propagation delays and output transition times.

TEST CIRCUIT

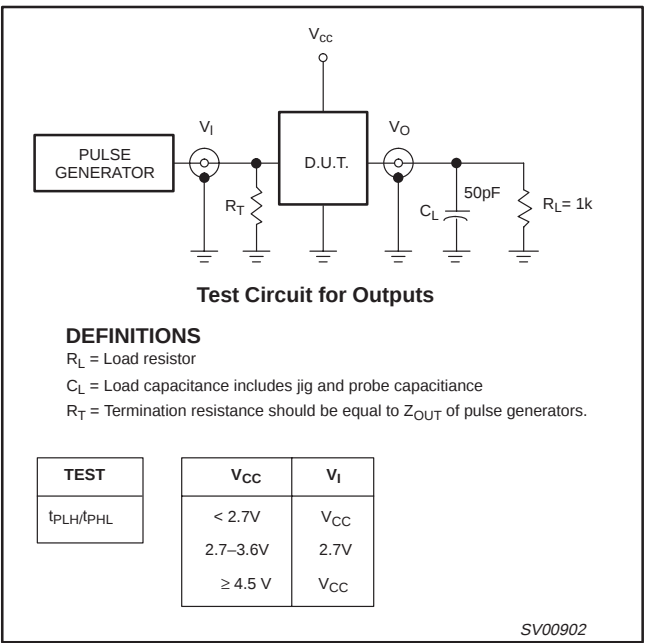


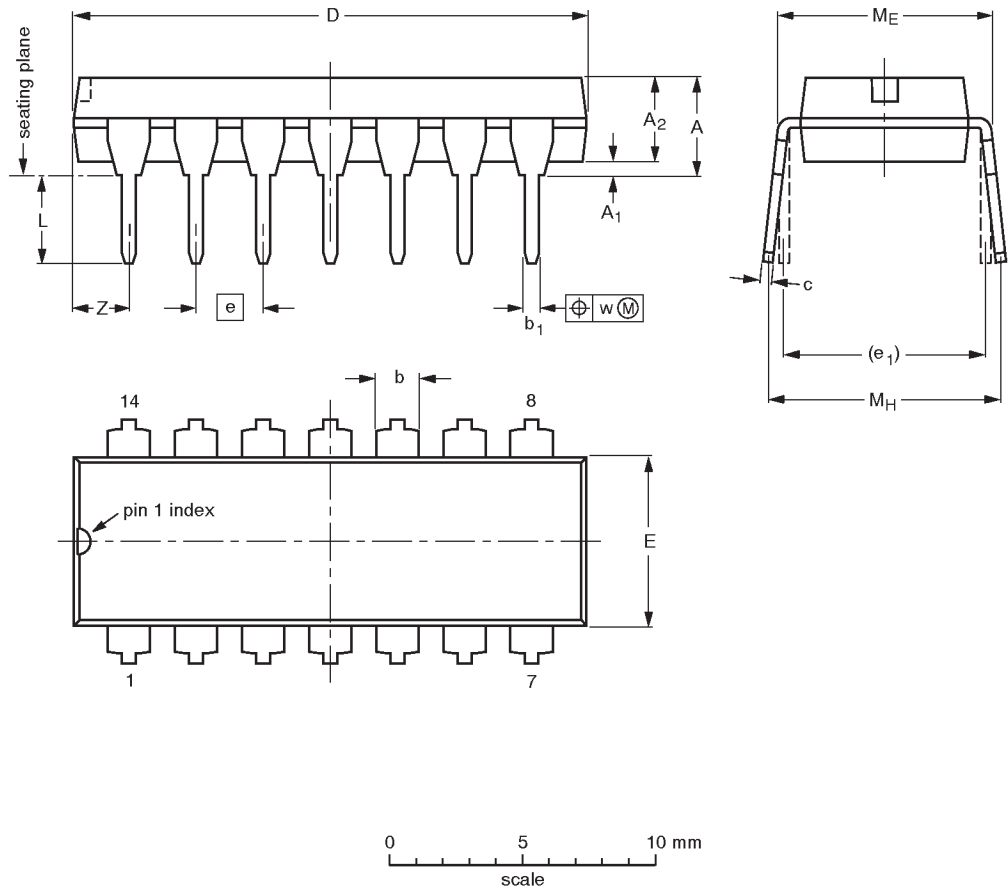
Figure 2. Load circuitry for switching times

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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

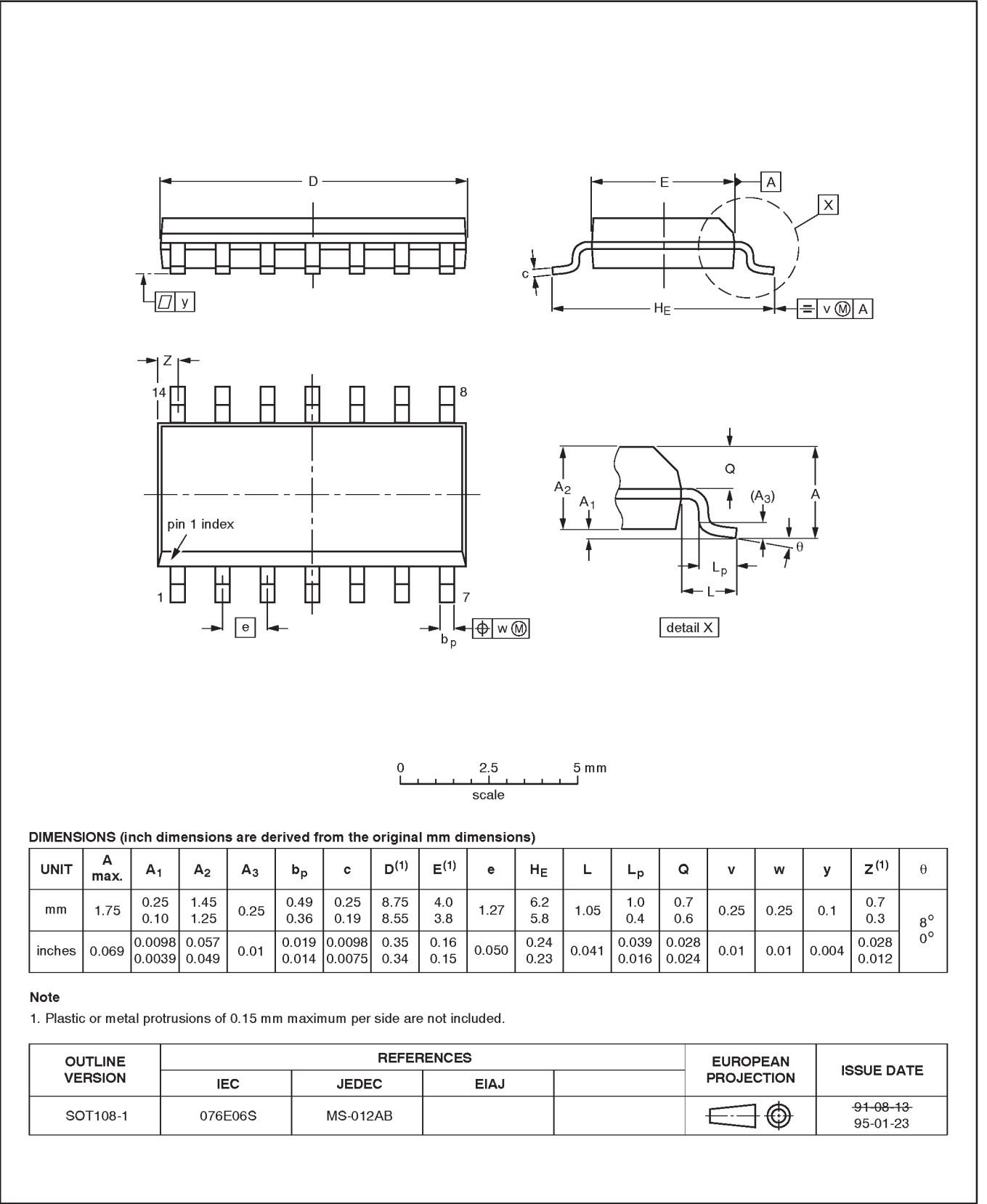
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

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SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

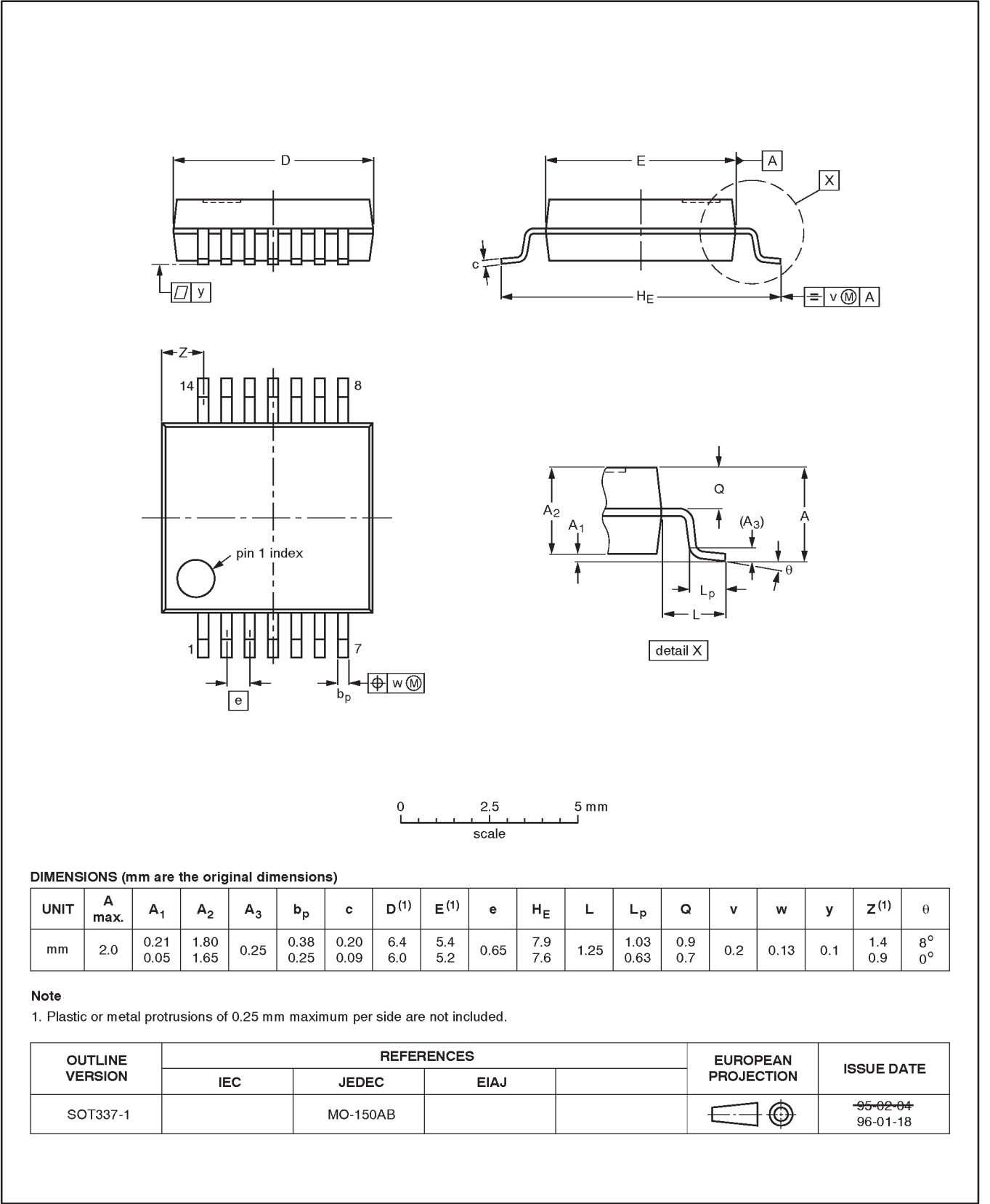


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SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

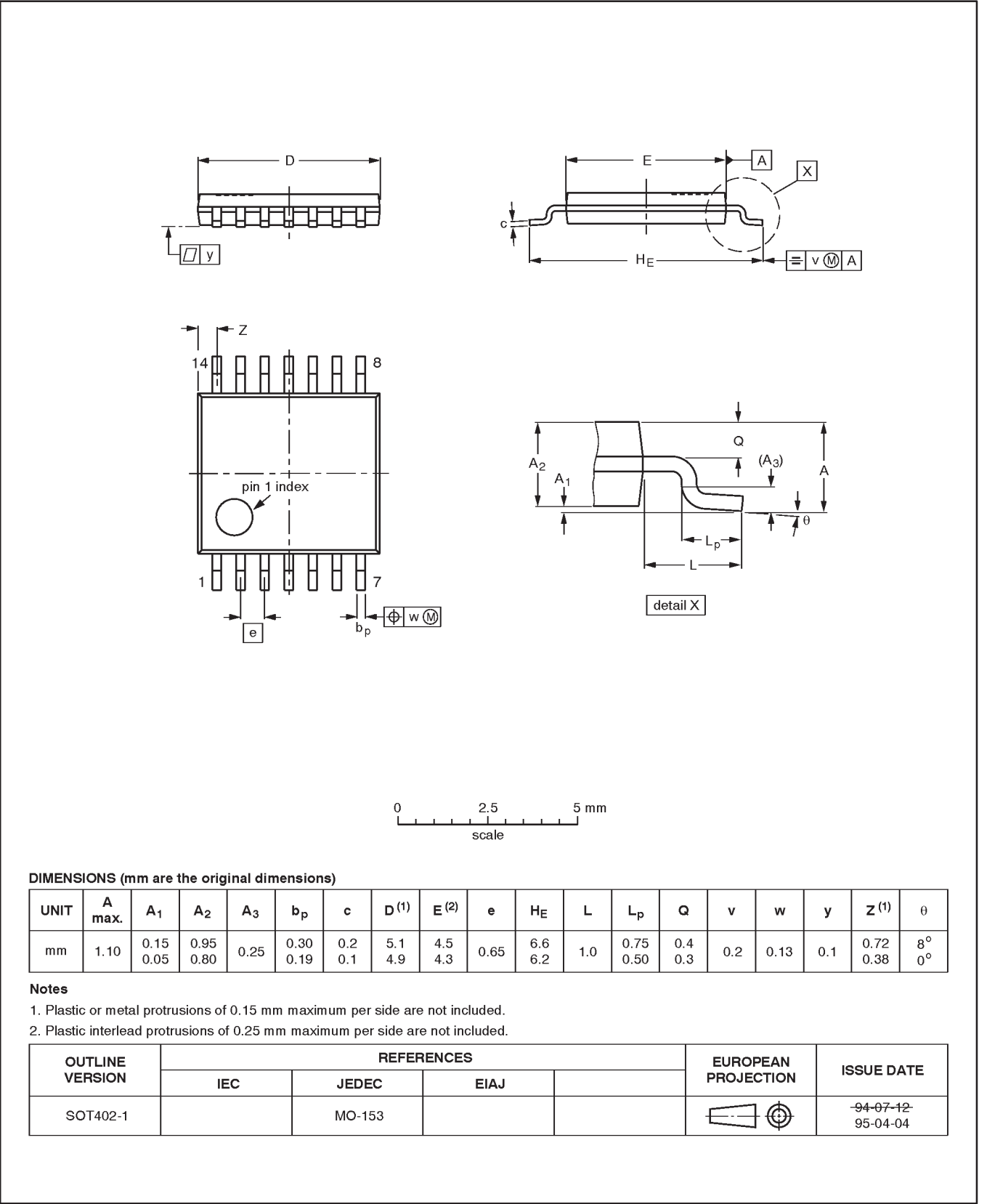


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TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



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DEFINITIONS		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

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